

Amendment and Claim Listing

Please amend claim 1 as follows:

Claim 1 (currently amended) A curing light comprising:
a wand for grasping by a human hand in order to manipulate the curing light, said wand having a longitudinal axis and a length L_W along its longitudinal axis,
controls on said wand for controlling transmission of light from the curing light,
an elongate heat sink located at least partially within said wand, said elongate heat sink having a proximal end, a distal end and a longitudinal axis therebetween, said elongate heat sink having a length L_H ,
a mounting platform located at said elongate heat sink distal end,
a primary heat sink mounted to said mounting platform, said primary heat sink being smaller in overall volume than said elongate heat sink,
a well located on said primary heat sink, and
a light emitting semiconductor device mounted in said well of said primary heat sink;
wherein L_H is a substantial percentage of L_W ; and
wherein light emitted from said light emitting semiconductor device exits the curing light at an angular orientation with said wand longitudinal axis in the range of 30 to 150 degrees.

Claim 2 (original) A curing light as recited in claim 1 wherein L_H is less than about 50% of L_W .

Claim 3 (original) A curing light as recited in claim 1 wherein L_H more than about 50% of L_W .

Claim 4 (original) A curing light as recited in claim 1 wherein L_H is more than about 60% of L_W .

Claim 5 (original) A curing light as recited in claim 1 wherein L_H more than about 70% of L_W .

Claim 6 (original) A curing light as recited in claim 1 wherein L_H is more than about 80% of L_W .

Claim 7 (original) A curing light as recited in claim 1 wherein L_H more than about 90% of L_W .

Claim 8 (original) A curing light as recited in claim 1 wherein L_H is more than about 90% of L_W .

Claim 9 (original) A curing light as recited in claim 1 wherein L_H is up to about 100% of L_W .

Please amend claim 10 as follows:

Claim 10 (original) A curing light comprising:

 a wand for grasping by a human hand in order to manipulate the curing light, said wand having a longitudinal axis and a length L_W along its longitudinal axis,

 controls on said wand for controlling transmission of light from the curing light,

 an elongate heat sink located at least partially within said wand, said elongate heat sink having a proximal end, a distal end and a longitudinal axis therebetween, said elongate heat sink having a length L_H , and

 a light emitting semiconductor device mounted at said elongate heat sink distal end, said light emitting semiconductor device having a plurality of epitaxial layers, at least one of said epitaxial layers emitting photons when bombarded by electrons;

wherein at least some light emitted by said light emitting semiconductor device departs from the curing light at an angular orientation in the range of from about 30 to about 150 degrees with respect to said wand longitudinal axis.

Claim 11 (original) A curing light as recited in claim 10 wherein L_H is less than about 50% of L_W .

Claim 12 (original) A curing light as recited in claim 10 wherein L_H more than about 50% of L_W .

Claim 13 (original) A curing light as recited in claim 10 wherein L_H is more than about 60% of L_W .

Claim 14 (original) A curing light as recited in claim 10 wherein L_H more than about 70% of L_W .

Claim 15 (original) A curing light as recited in claim 10 wherein L_H is more than about 80% of L_W .

Claim 16 (original) A curing light as recited in claim 10 wherein L_H more than about 90% of L_W .

Claim 17 (original) A curing light as recited in claim 10 wherein L_H is more than about 90% of L_W .

Claim 18 (original) A curing light as recited in claim 10 wherein L_H is up to about 100% of L_W .

Claim 19 (original) A curing light as recited in claim 10 wherein said light emitting semiconductor device is selected from the group consisting of light emitting diode chips, laser chips, light emitting diode chip array, diode laser chips, diode laser chip arrays, surface emitting laser chips, edge emitting laser chips, and VCSEL chips.